# 2SD2136

## Silicon NPN triple diffusion planar type

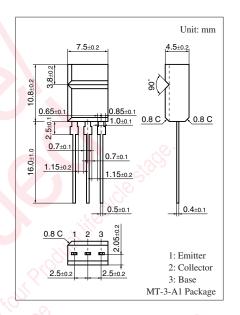
For power amplification Complementary to 2SB1416

#### ■ Features

- High forward current transfer ratio h<sub>FE</sub> which has satisfactory linearity.
- $\bullet$  Low collector-emitter saturation voltage  $V_{\text{CE}(\text{sat})}$
- Allowing supply with the radial taping

### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	60	V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	60	V
Emitter-base voltage (Collector open)	$V_{EBO}$	6	V
Collector current	$I_{C}$	3	A
Peak collector current	$I_{CP}$	5	A
Collector power dissipation	$P_{C}$	1.5	W
Junction temperature	T <sub>j</sub>	150	°C ,
Storage temperature	T <sub>stg</sub>	-55 to +150	°C



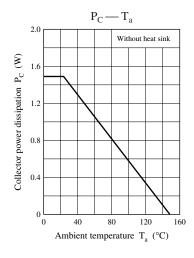
### ■ Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

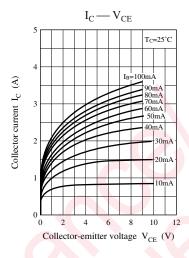
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_C = 30 \text{ mA}, I_B = 0$	60	, YIC	•	V
Base-emitter voltage *1	$V_{BE}$	$V_{CE} = 4 \text{ V}, I_{C} = 3 \text{ A}$	100	80,	1.8	V
Collector-emitter cutoff current (Emitter-base short)	I <sub>CES</sub>	$V_{CE} = 60 \text{ V}, V_{BE} = 0$		)·	200	μΑ
Collector-emitter cutoff current (Base open)	$I_{CEO}$	$V_{CE} = 30 \text{ V}, I_{B} = 0$	7.60		300	μΑ
Emitter-base cutoff current (Collector open)	$I_{EBO}$	$V_{EB} = 6 \text{ V}, I_{C} = 0$			1	mA
Forward current transfer ratio	h <sub>FE1</sub> *2	$V_{CE} = 4 \text{ V}, I_{C} = 1 \text{ A}$	40		250	_
	h <sub>FE2</sub> *1	$V_{CE} = 4 \text{ V}, I_{C} = 3 \text{ A}$	10			
Collector-emitter saturation voltage *1	V <sub>CE(sat)</sub>	$I_C = 3 \text{ A}, I_B = 0.375 \text{ A}$			1.2	V
Transition frequency	$f_T$	$V_{CE} = 5 \text{ V}, I_{E} = -0.1 \text{ A}, f = 200 \text{ MHz}$		220		MHz
Turn-on time	t <sub>on</sub>	$I_C = 1 \text{ A}, I_{B1} = 0.1 \text{ A}, I_{B2} = -0.1 \text{ A}$		0.5		μs
Storage time	t <sub>stg</sub>			2.5		μs
Fall time	t <sub>f</sub>			0.4		μs

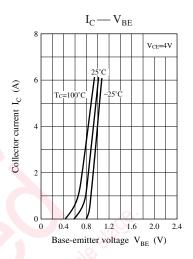
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

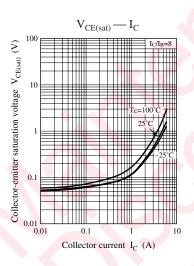
- 2. \*1: Pulse measurement
  - \*2: Rank classification

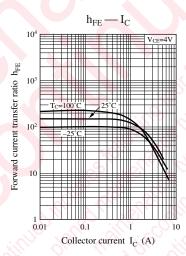
Rank	Р	Q	R
$h_{FE1}$	40 to 90	70 to 150	120 to 250

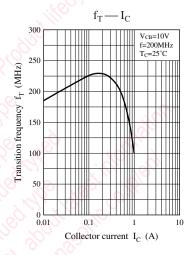


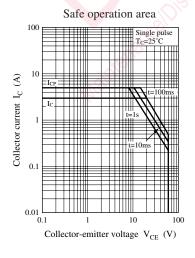


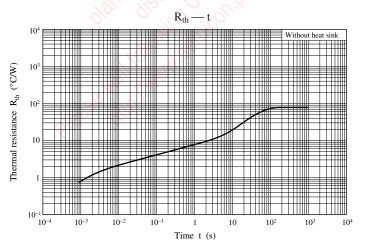












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